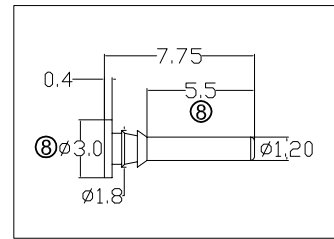
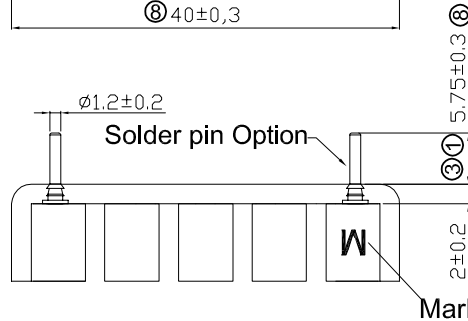
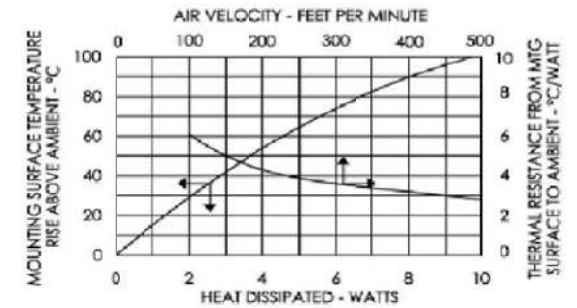


Depth: 0,1mm
TIA806FG Foil with pull tab Option
Size: 15x15mm



③ Detail Pin
2 : 1

- Notes:
Material: AL 1050
Finish: Nature anodized
Pin material: Fe
Plating: Tin
④ Recommended IC size: ≤ 30x30mm
Recommended IC power: ≤ 5W
④ WSW order code:
V2136N: w/o foil, w/o solder pin
V2136N1: w/o foil, with solder pin
V2136N1-F: with foil, w/o solder pin
V2136N1-F-LP: with foil & with solder pin



RoHS compliant
Unit: mm

| Scale | Free | ⑧ | Update tolerance | 29.05.2018 | Segal | | Date | Name | Customer-No. |
|-------------|-------|-----|--------------------------------|------------|-------|----------|------------|------|-------------------------------------|
| ⑧ TOLERANCE | | ⑦ | Add IC size and power in notes | 22.05.2018 | Amy | Drawn | 02.05.2013 | Amy | ASSMANN WSW-No. V2136Nx-x |
| Less 10 | ±0.10 | ⑥ | Change the foil on page 2/3 | 23.06.2016 | Amy | Approved | 29.05.2018 | Amy | |
| 10~30 | ±0.20 | ⑤ | Add thermal resistance graph | 19.02.2016 | Amy | | | | Drawing-No. |
| 31~50 | ±0.30 | ④ | Add new version | 25.01.2016 | Amy | | | | ASS 2103 HS |
| 51~100 | ±0.50 | ③ | Update the solder pin | 21.05.2015 | Amy | | | | rev08 |
| DIM | Tol | | | | | | | | Sheet |
| Angle | ±1° | Id. | Modification | Date | Name | | | | 1 / 3 |

A

B

C

D

E

F

G

H

A

B

C

D

E

F

G

H


TIA 806FG product is mostly used for bonding heat dissipation fins, microprocessors and other power consumption semiconductors. This type of adhesive tape possesses ultimate bonding strength with low thermal impedance, with which in effect can be able to replace the method of lubricating grease and mechanical fixing.

Feature
 Thermal Conductivity 1.0W/mK
 High bond strength to a variety of surfaces
 Double sided pressure sensitive adhesive tape
 High performance, thermally conductive acrylic adhesive

Application
 Mount heat sink onto BAG graphic processor or drive processor
 Mount heat spreader onto power converter PCB or onto motor control PCB
 High performance, thermally conductive acrylic adhesive
 Can be used instead of heat cure adhesive, screw mounting or clip mounting

| Typical Properties | TIA™806FG | | | Test Method |
|-----------------------------|--|--------------------|-------------|-------------|
| Color | White | | | Visual |
| Adhesive Type | Acrylic Adhesive | | | ***** |
| Backing Type | Fiberglass | | | ***** |
| Continuous Use Temp | -45 °C to 120 °C | | | ***** |
| Thickness | 0.006" | | | ASTM D374 |
| Thickness Tolerance | 0.152mm ±0.001" ±0.025mm | | | ASTM D374 |
| Voltage Breakdown | > 3000 Vac | | | ASTM D149 |
| Tensile Strength | 120psi | | | ASTM D412 |
| Thermal Impedance @50psi | 0.59°C-in²/W | | | ASTM D5470 |
| Thermal Conductivity | 1.0 W/mK | | | ASTM D5470 |
| Peel Adhesion | > 1000 g/inch (Steel, Immediate) | | | PSTC-1 |
| Peel Adhesion | > 1200 g/inch (Steel after 24 hrs) | | | PSTC-1 |
| Holding Power (25 °C/Hours) | > 48 Hours | | | PSTC-7 |
| Holding Power (80 °C/Hours) | > 48 Hours | | | PSTC-7 |
| Recommend Using Pressure | Pressure | Temperature | Time | ***** |
| | 10 psi (0.069 MPa) | 25°C | 20 sec | |
| | 10 psi (0.069 MPa) | 50 °C - 65 °C | 5 sec | |
| Shelf Life | 1 year when stored at room temperature | | | ***** |

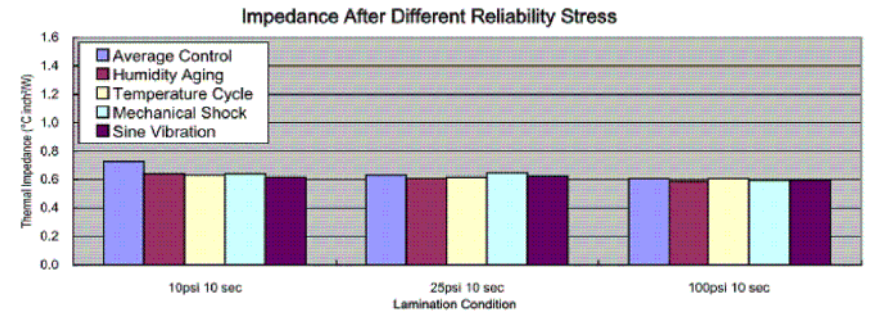
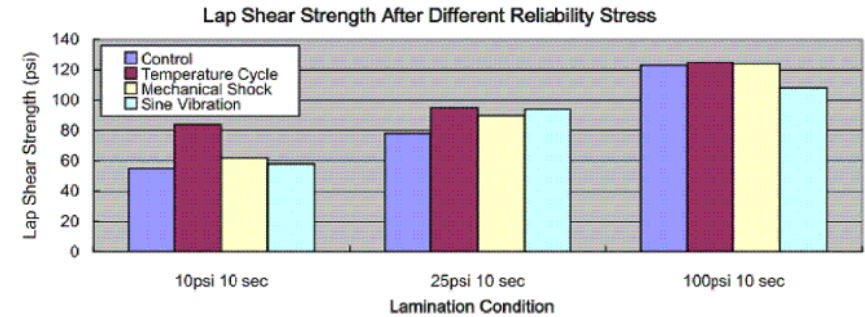
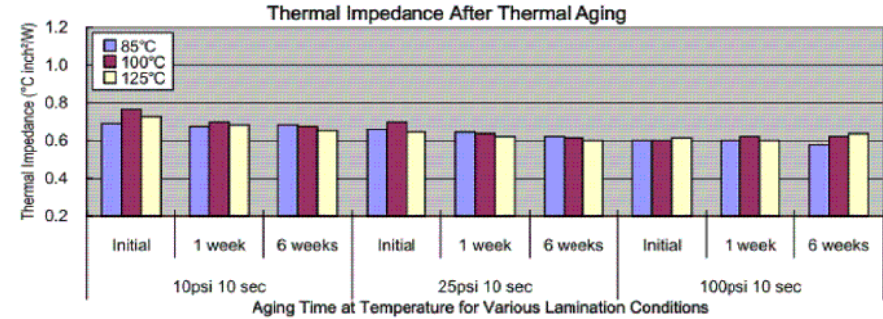
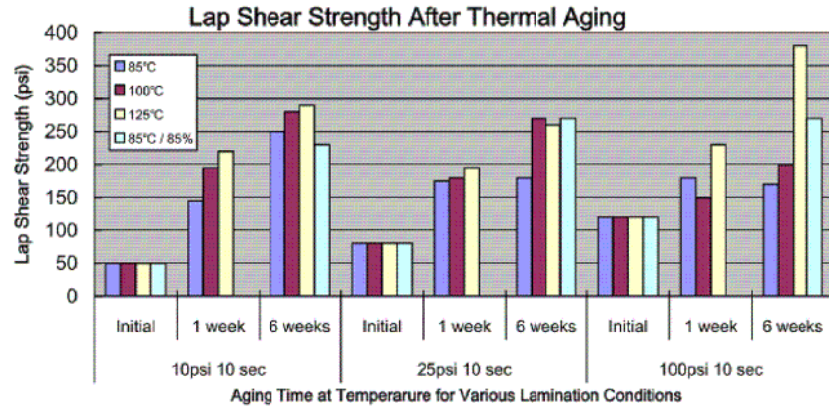
RoHS compliant
 Unit: mm

| Scale | Free | ⑧ | Update tolerance | 29.05.2018 | Segal | | Date | Name | Customer-No. |
|-------------|-------|-----|--------------------------------|------------|-------|---|------------|------|---|
| ⑧ TOLERANCE | | ⑦ | Add IC size and power in notes | 22.05.2018 | Amy | Drawn | 02.05.2013 | Amy | ASSMANN WSW-No. V2136Nx-x |
| Less 10 | ±0.10 | ⑥ | Change the foil on page 2/3 | 23.06.2016 | Amy | Approved | 29.05.2018 | Amy | |
| 10~30 | ±0.20 | ⑤ | Add thermal resistance graph | 19.02.2016 | Amy | | | | |
| 31~50 | ±0.30 | ④ | Add new version | 25.01.2016 | Amy | | | | Drawing-No. |
| 51~100 | ±0.50 | ③ | Update the solder pin | 21.05.2015 | Amy | | | | ASS 2103 HS |
| DIM | Tol | | | | | | | | rev08 |
| Angle | ±1° | Id. | Modification | Date | Name |  | | | Replace |
| | | | | | | | | | Sheet 2 / 3 |

Thermal Cycling Reliability Test TIA806FG

The long term reliability of TIA806FG tape was evaluated. Lap shear strength and thermal impedance were measured after exposing to various aging environments. Lap shear samples were prepared by sandwiching TIA806FG tape between Al substrates with 1x1 inch² overlap. Thermal samples for reliability testing were also prepared by laminating the tape between Al substrates at various pressures. TIA806FG exhibits excellent stability and passes thermal and adhesion properties after various aging conditions.

- Thermal aging: 1000 hours at three different temperatures: 85°C, 100°C and 125°C
- Thermal/ humidity aging: 1000 hours at 85°C/85% relative humidity
- Thermal shock: temperature ramp from -40 to 125°C at a rate of 10°C/minute with 10 minute hold at peaks for 100 cycles
- Mechanical shock: 3 blows in 6 directions (total of 18) with 60G's force in half sine pulse
- Sine vibration: vibration between 10 to 2000Hz with 2grams to 12grams force on X and Y axis only



RoHS compliant
Unit: mm

| Scale | Free | ⑧ | Update tolerance | 29.05.2018 | Segal | | Date | Name | Customer-No. |
|-------------|-------|-----|--------------------------------|------------|-------|-------------------------------|------------|---------|-------------------------------------|
| ⑧ TOLERANCE | | ⑦ | Add IC size and power in notes | 22.05.2018 | Amy | Drawn | 02.05.2013 | Amy | ASSMANN WSW-No. V2136Nx-x |
| Less 10 | ±0.10 | ⑥ | Change the foil on page 2/3 | 23.06.2016 | Amy | Approved | 29.05.2018 | Amy | |
| 10~30 | ±0.20 | ⑤ | Add thermal resistance graph | 19.02.2016 | Amy | | | | |
| 31~50 | ±0.30 | ④ | Add new version | 25.01.2016 | Amy | | | | |
| 51~100 | ±0.50 | ③ | Update the solder pin | 21.05.2015 | Amy | | | | Drawing-No. |
| DIM | Tol | | | | | | | | ASS 2103 HS |
| Angle | ±1° | Id. | Modification | Date | Name | ASSMANN WSW components | | Replace | rev08 |
| | | | | | | | | Sheet | 3 / 3 |